

01-08-2003

Commissioner of Patents & Trademarks

Washington, D.C. 20231

Form PTO-1595

(Rev. 03/01)

12/30/02



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U.S. DEPARTMENT OF COMMERCE

U.S. PATENT AND TRADEMARK OFFICE

To the honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof:

1. Name of Conveying Party(ies):

YOON, DONG-SOO

2. Name and Address of Receiving Party(ies):

Name: Hynix Semiconductor Inc.

Street Address: San 136-1, Ami-ri, Bubal-eub

Street Address:

City: Ichon-shi, Kyoungki-do

State/Country: Korea Postal Code: 467-860

Additional name(s) of conveying party(ies) attached?  Yes  No

Additional name(s) and addresses attached?  Yes  No

3. Nature of Conveyance:

Assignment

Change of Name

Security Agreement

Other:

Merger

Execution Date: 12302002

4. Application Number(s) or Patent Number(s):

Assignment is being filed together with new application and the first execution date of application is: 12302002

Application has been filed already and the application filing date is:

A. Patent Application Number(s):

B. Issued Patent Number(s):

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning this matter should be mailed:

CUSTOMER NUMBER 00136 -or-

JACOBSON HOLMAN PLLC  
400 Seventh Street, N.W.  
Washington, D.C. 20004-2218  
Tel. 202-638-6666

Attorney Docket Number: P68542US0

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41): \$ 40.00

Enclosed

Any deficiencies in enclosed fees are authorized to be charged to Deposit Account No. 06-1358.

DO NOT USE THIS SPACE

8. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Yoon S. Ham/45,307

December 30, 2002

Name of Person Signing, Reg. No.

Signature

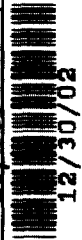
Date

Total number of pages including cover sheet, attachments, and documents:

-2-

JCH 103-2/02

J1042 U.S. PTO  
10/330129



12/30/02

**UNITED STATES OF AMERICA-ASSIGNMENT**

(1-6) Insert Name(s) of Inventors

- (1) YOON, DONG-SOO
- (2) \_\_\_\_\_
- (3) \_\_\_\_\_
- (4) \_\_\_\_\_
- (5) \_\_\_\_\_
- (6) \_\_\_\_\_

In consideration of the sum of one dollar (\$1.00), and other good and valuable considerations paid to each of the undersigned, the receipt and sufficiency of which are hereby acknowledged, the undersigned agree(s) to assign, transfer and set over to

(7) Insert Name of assignee

(7) Hynix Semiconductor Inc.

(8) Insert Address of Assignee

(8) of San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860,  
Republic of Korea

(9) Insert Legal Entity and State or Country (e.g., a corporation or citizen of Japan)

(9) a Corporation of Republic of Korea  
(hereinafter designated as the Assignee) the entire right, title and interest for the United States, its territories, dependencies and possessions, in the invention known as

(10) insert Identification of Invention, such as Title, Case Number or Foreign Application Number

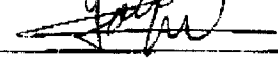
(10) HYDROGEN BARRIER LAYER AND METHOD FOR FABRICATING  
SEMICONDUCTOR DEVICE HAVING THE SAME

(11) Insert Date of Signing of Application, or filing date and Serial No., if known

(11) Said application having been executed/filed on December 30, 2002 (and assigned Serial No. New Application)

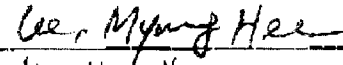
- 1) The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such application as the Assignee may deem necessary or expedient.
- 2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuing or divisional applications thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.
- 3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Union for Protection of Industrial Property or similar agreements.
- 4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.
- 5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States resulting from this application or any continuing or divisional applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.
- 6) The undersigned hereby grant(s) the law firm of Jacobson, Price, Holman & Stern, 400 Seventh Street, N.W., Washington, D.C. 20004, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

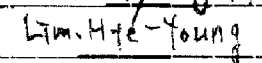
In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date	<u>December 30, 2002</u>	Name of Inventor	<u>YOON, DONG-SOO</u>		(SEAL)
Date	_____	Name of Inventor	typed name	_____	(SEAL)
Date	_____	Name of Inventor	typed name	_____	(SEAL)
Date	_____	Name of Inventor	typed name	_____	(SEAL)
Date	_____	Name of Inventor	typed name	_____	(SEAL)
Date	_____	Name of Inventor	typed name	_____	(SEAL)

This assignment should preferably be signed before a United States Consul if signed abroad, or a Notary public if domestically signed. If not, then the execution by the inventor(s) should be witnessed by at least two witnesses who sign here:

A additional inventor's names and signatures on a separate sheet.

Witness LEE, MYUNG-HEE 

Witness LIM, HYE-YOUNG 

LAW OFFICES OF  
**JACOBSON, PRICE, HOLMAN & STERN**  
THE JENIFER BUILDING  
400 SEVENTH STREET, N.W.  
WASHINGTON, D.C. 20004

**PATENT**